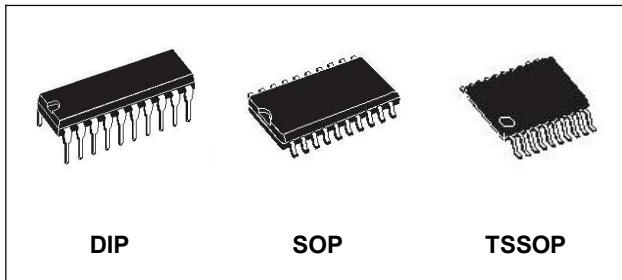


OCTAL D-TYPE FLIP FLOP WITH 3 STATE OUTPUT NON INVERTING

Datasheet- production data



Description

The RD74HC374 is a high-speed CMOS OCTAL D-TYPE FLIP FLOP WITH 3-STATE OUTPUTS NON-INVERTING fabricated with sub-micron silicon gate CMOS technology.

This 8-bit D-TYPE FLIP FLOP is controlled by a clock input (CK) and an output enable input (\overline{OE}). On the positive transition of the clock, the Q outputs will be set to the logic state that were setup at the D inputs.

While the \overline{OE} input is at low level, the eight outputs will be in a normal logic state (high or low logic level) and while \overline{OE} is high the outputs will be in a high impedance state.

The output control does not affect the internal operation of flip-flops; that is, the old data can be retained or the new data can be entered even while the outputs are off.

All inputs are equipped with protection circuits against static discharge and transient excess voltage.

Features

- HIGH SPEED:
 $f_{MAX} = 90\text{MHz}$ (TYP.) at $V_{CC} = 6\text{V}$
- LOW POWER DISSIPATION:
 $I_{CC} = 4\mu\text{A}$ (MAX.) at $T_A=25^\circ\text{C}$
- HIGH NOISE IMMUNITY:
 $V_{NIH} = V_{NIL} = 28\% V_{CC}(\text{MIN.})$
- SYMMETRICAL OUTPUT IMPEDANCE:
 $|I_{OH}| = I_{OL} = 6\text{mA}$ (MIN.)
- BALANCED PROPAGATION DELAYS:
 $t_{PLH} \approx t_{PHL}$
- WIDE OPERATING VOLTAGE RANGE:
 $V_{CC}(\text{OPR}) = 2\text{V}$ to 6V

Table 1. Device summary

PART NUMBER	PACKAGE
RD74HC374BDI	DIP20
RD74HC374BSO	SOP20
RD74HC374BTS	TSSOP20

1 Pin information

Figure 1. Pin connection and IEC logic symbols

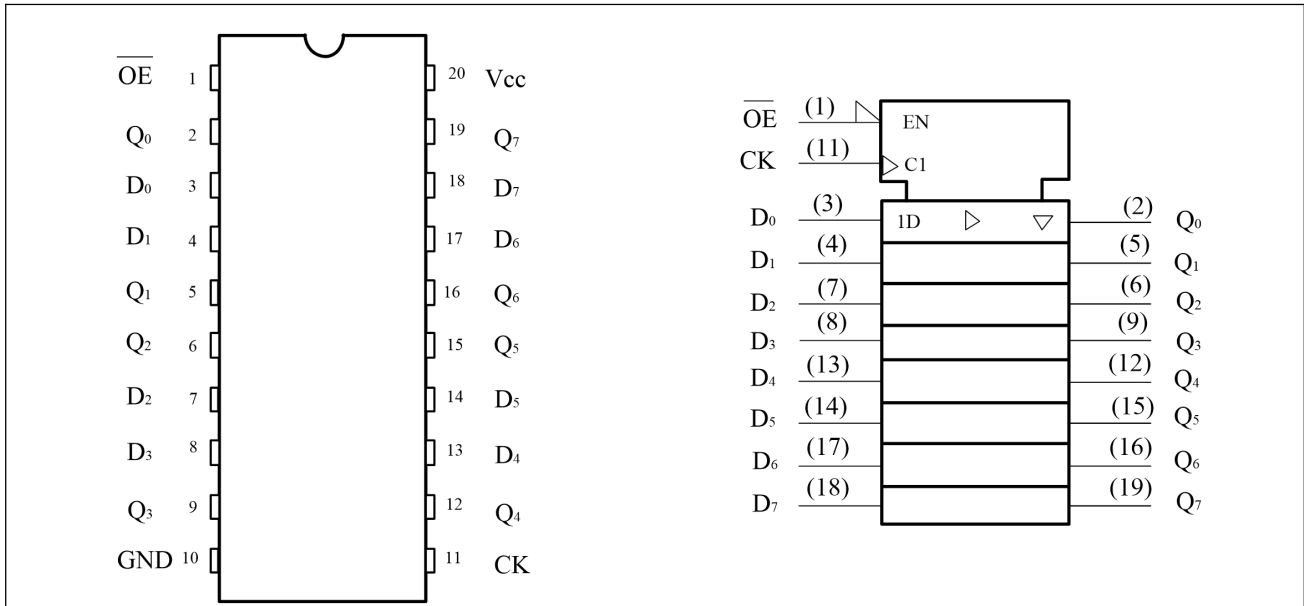





Table 2. Pin description

Pin No	Symbol	Name and function
1	$\overline{\text{OE}}$	3 State Output Enable Input (Active LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q ₀ to Q ₇	3 State Outputs
3, 4, 7, 8, 13, 14, 17, 18	D ₀ to D ₇	Data Inputs
11	CK	Clock Input (LOW to HIGH, Edge Triggered)
10	GND	Ground (0V)
20	V _{CC}	Positive Supply Voltage

2 Functional description

Table 3. Truth table

INPUTS			OUTPUTS
$\overline{\text{OE}}$	CK	D	Q
H	X	X	Z
L		X	NO CHANGE
L		L	L
L		H	H

X = Don't care
Z = High impedance

Figure 2. Input and output equivalent circuit

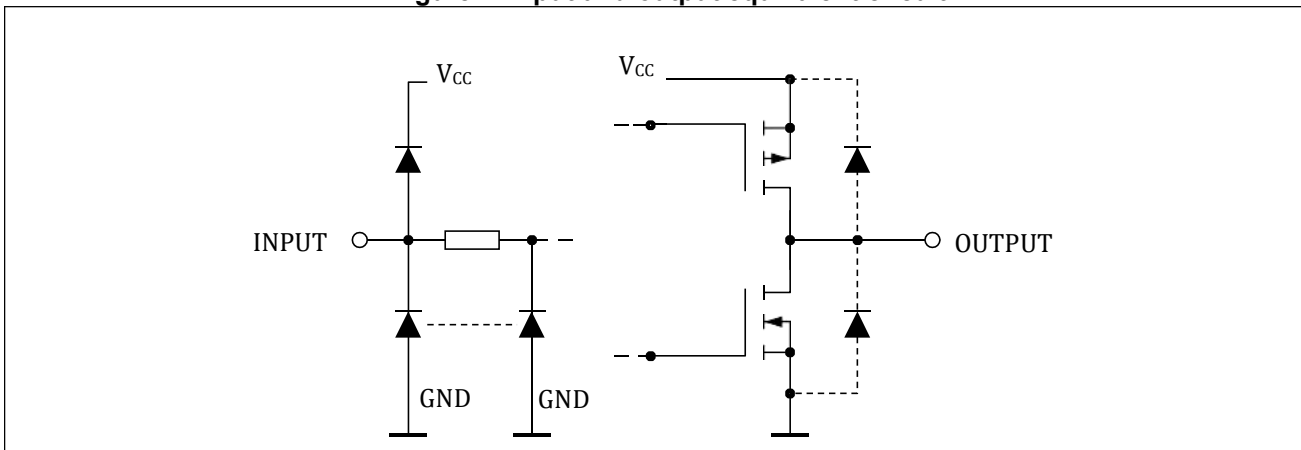
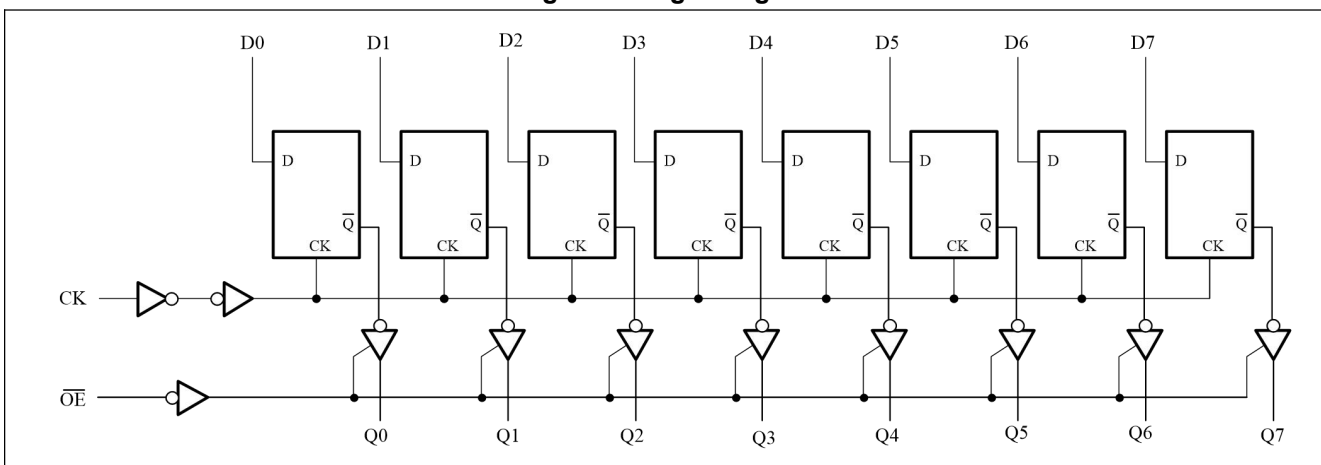


Figure 3. Logic diagram



This logic diagram has not be used to estimate propagation delays

3 Electrical characteristics

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply Voltage	-0.5 to + 7.0	V
V_I	DC Input Voltage	-0.5 to $V_{CC} + 0.5$	V
V_O	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current	± 20	mA
I_{OK}	DC Output Diode Current	± 20	mA
I_O	DC Output Current	± 35	mA
I_{CC} or I_{GND}	DC Vcc or Ground Current	± 70	mA
P_D	Power Dissipation	500 (*)	mW
T_{stg}	Storage Temperature	-65 to + 150	$^{\circ}C$
T_L	Lead Temperature (10 sec)	300	$^{\circ}C$

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied

(*) 500mW at 65 $^{\circ}C$; derate to 300mW by 10mW/ $^{\circ}C$ from 65 $^{\circ}C$ to 85 $^{\circ}C$

Table 5. Recommended operating conditions

Symbol	Parameter	Value	Unit	
V_{CC}	Supply Voltage	2 to 6	V	
V_I	Input Voltage	0 to V_{CC}	V	
V_O	Output Voltage	0 to V_{CC}	V	
T_{op}	Operating Temperature	-40 to +85	°C	
t_r, t_f	Input Rise and Fall Time	$V_{CC} = 2.0V$	0 to 1000	ns
		$V_{CC} = 4.5V$	0 to 500	ns
		$V_{CC} = 6.0V$	0 to 400	ns

Table 6. DC specifications

Symbol	Parameter	Test Condition		Value					Unit
		V_{CC} (V)		$T_A = 25\text{ °C}$			-40 to 85°C		
				Min	Typ	Max	Min	Max	
V_{IH}	High Level Input Voltage	2.0		1.5			1.5		V
		4.5		3.15			3.15		
		6.0		4.2			4.2		
V_{IL}	Low Level Input Voltage	2.0				0.5		0.5	V
		4.5				1.35		1.35	
		6.0				1.8		1.8	
V_{OH}	High Level Output Voltage	2.0	$I_O = -20\mu A$	1.9	2.0		1.9		V
		4.5	$I_O = -20\mu A$	4.4	4.5		4.4		
		6.0	$I_O = -20\mu A$	5.9	6.0		5.9		
		4.5	$I_O = -6.0\text{ mA}$	4.18	4.31		4.13		
		6.0	$I_O = -7.8\text{ mA}$	5.68	5.8		5.63		
V_{OL}	Low Level Output Voltage	2.0	$I_O = 20\mu A$		0.0	0.1		0.1	V
		4.5	$I_O = 20\mu A$		0.0	0.1		0.1	
		6.0	$I_O = 20\mu A$		0.0	0.1		0.1	
		4.5	$I_O = 6.0\text{ mA}$		0.17	0.26		0.33	
		6.0	$I_O = 7.8\text{ mA}$		0.18	0.26		0.33	
I_I	Input Leakage Current	6.0	$V_I = V_{CC}$ or GND			± 0.1		± 1	μA
I_{OZ}	High Impedance Output Leakage Current	6.0	$V_I = V_{IH}$ or V_{IL} $V_O = V_{CC}$ or GND			± 0.5		± 5	μA
I_{CC}	Quiescent Supply Current	6.0	$V_I = V_{CC}$ or GND			4		40	μA

Table 7. AC electrical characteristics ($C_L = 50\text{pF}$, Input $t_r = t_f = 6\text{ns}$)

Symbol	Parameter	Test Condition			Value					Unit
		V_{CC} (V)	C_L (pF)		$T_A = 25^\circ\text{C}$			-40 to 85°C		
					Min	Typ	Max	Min	Max	
$t_{TLH} t_{THL}$	Output Transition Time	2.0	50			25	60		75	ns
		4.5				7	12		15	
		6.0				6	10		13	
$t_{PLH} t_{PHL}$	Propagation Delay Time (CLOCK – Q)	2.0	50			45	140		175	ns
		4.5				15	28		35	
		6.0				13	24		30	
		2.0	150			60	190		240	ns
		4.5				20	38		48	
		6.0				17	32		41	
$t_{PZL} t_{PZH}$	High Impedance Output Enable Time	2.0	50	$R_L = 1\text{K}\Omega$		39	135		170	ns
		4.5				13	27		34	
		6.0				11	23		29	
		2.0	150	$R_L = 1\text{K}\Omega$		54	185		230	ns
		4.5				18	37		46	
		6.0				15	31		39	
$t_{PLZ} t_{PHZ}$	High Impedance Output Disable Time	2.0	50	$R_L = 1\text{K}\Omega$		30	125		155	ns
		4.5				14	25		31	
		6.0				13	21		26	
f_{MAX}	Maximum Clock Frequency	2.0	50		6.2	18		5		MHz
		4.5			31	75		25		
		6.0			37	90		30		
$t_{W(L)}$ $t_{W(H)}$	Minimum Pulse Width(CLOCK)	2.0	50			15	75		95	ns
		4.5				6	15		19	
		6.0				6	13		16	
t_s	Minimum Set-up Time	2.0	50			25	75		95	ns
		4.5				6	15		19	
		6.0				4	13		16	
t_h	Minimum Hold Time	2.0	50				0		0	ns
		4.5					0		0	
		6.0					0		0	

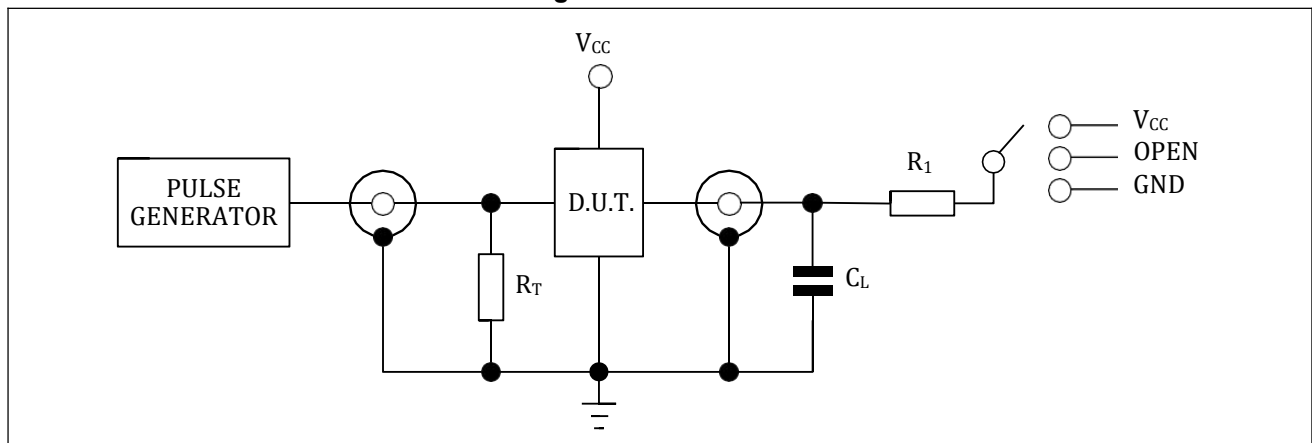
Table 8. Capacitive characteristics

Symbol	Parameter	Test Condition		Value					Unit
		V _{CC} (V)		T _A = 25°C			-40 to 85°C		
				Min	Typ	Max	Min	Max	
C _{IN}	Input Capacitance	5.0			5	10		10	pF
C _{OUT}	Output Capacitance	5.0			10				pF
C _{PD}	Power Dissipation Capacitance ⁽¹⁾	5.0			47				pF

1. C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to test circuit). Average operating current can be obtained by the following equation:
 $I_{CC(OPR)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/8$ (per Flip Flop) and the C_{PD} when n pcs of Flip Flop operate, can be gained by the following equation: $C_{PD(TOTAL)} = 30 + 17 \times n$ (pF)

4 Test circuit

Figure 4. Test circuit



TEST	SWITCH
t _{PLH} , t _{PHL}	OPEN
t _{PZL} , t _{PLZ}	V _{CC}
t _{PZH} , t _{PHZ}	GND

R_T = Z_{OUT} of pulse generator (typically 50Ω)

R₁ = 1KΩ or equivalent

C_L = 50pF/150pF or equivalent (includes jig and probe capacitance)

Figure 5. Waveform 1: CK to Qn propagation delays, CK f_{MAX} , Dn to CK setup and hold time (f=1MHz; 50% duty cycle)

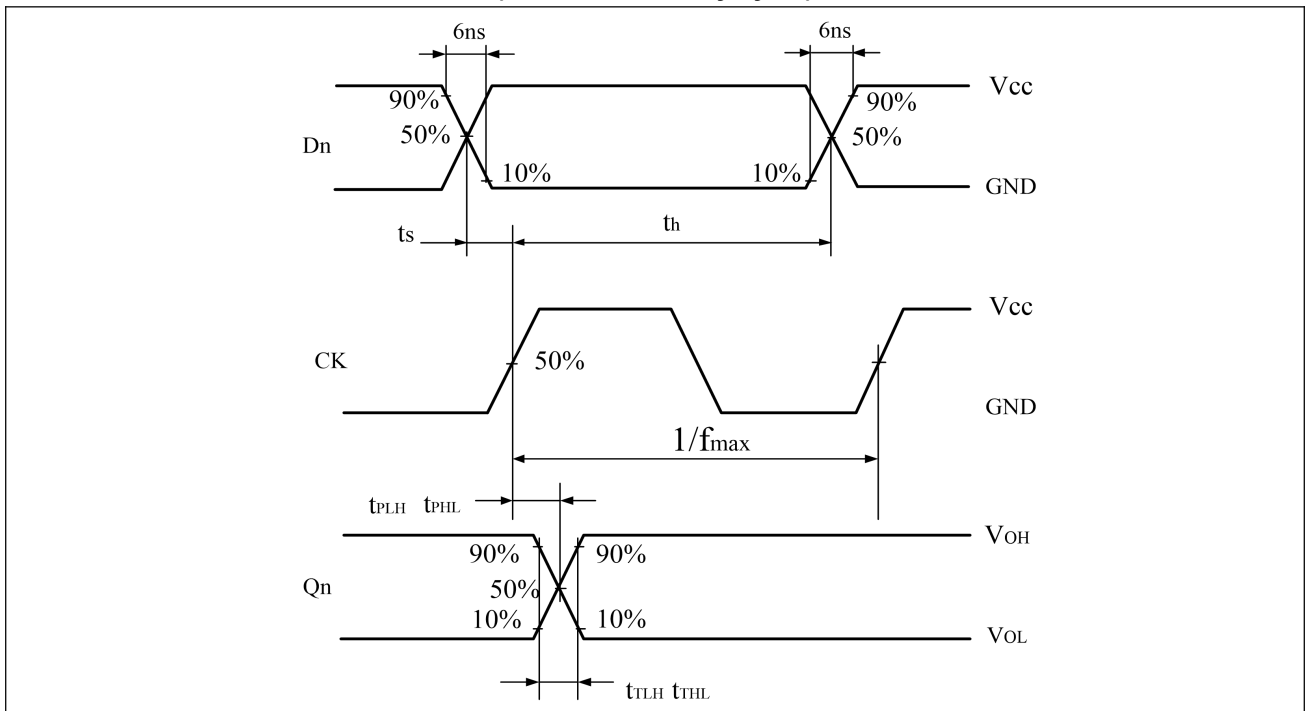


Figure 6. Waveform 2: output enable and disable times (f= 1MHz; 50% duty cycle)

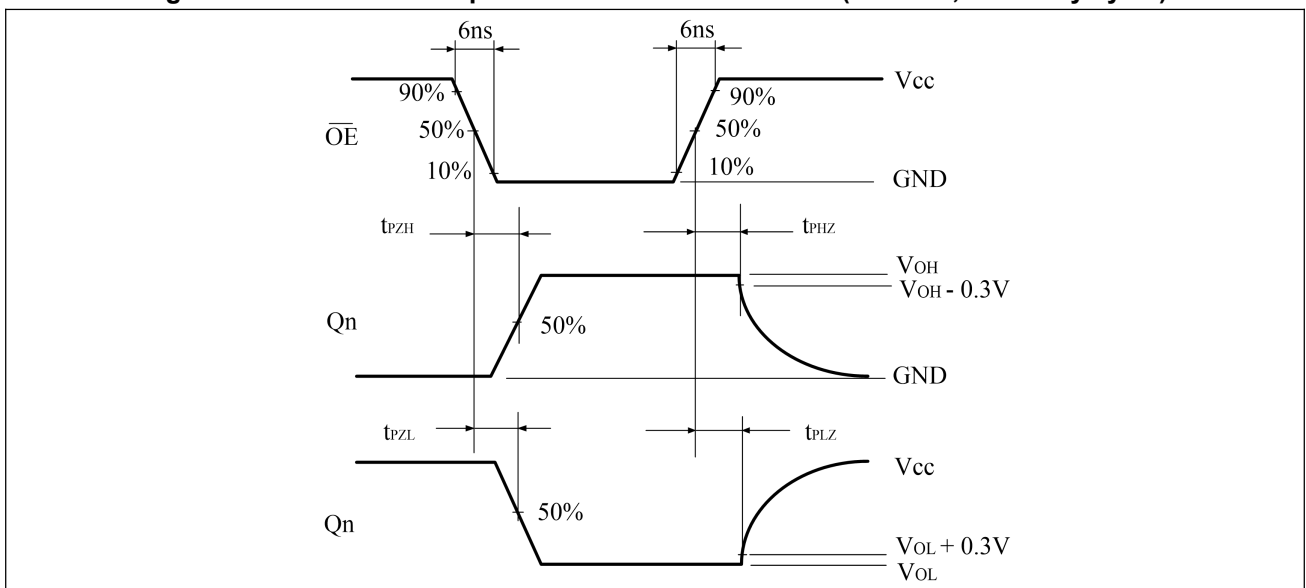
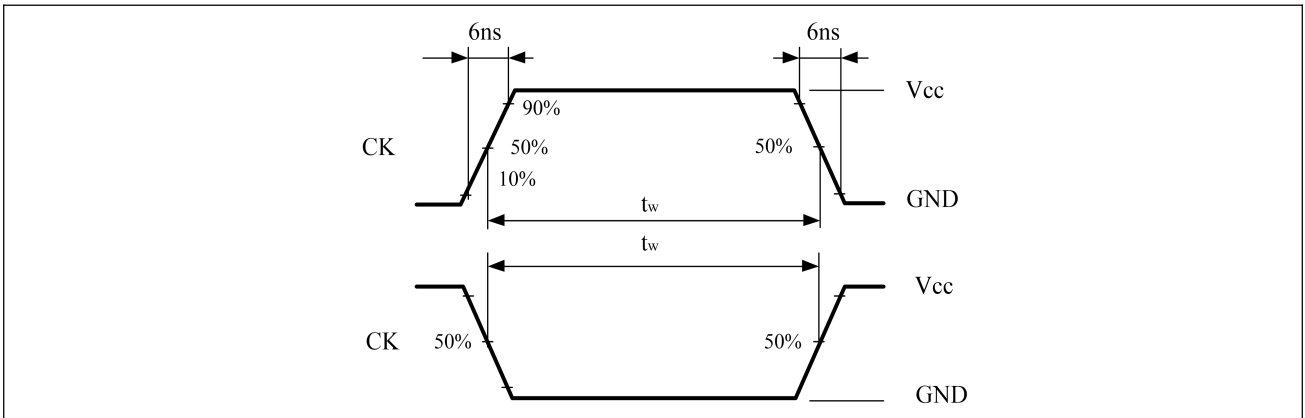


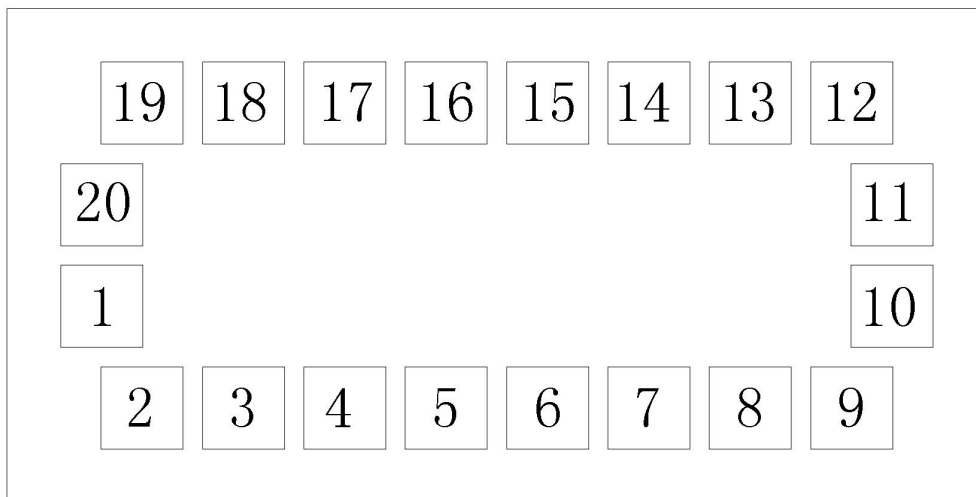
Figure 7. Waveform 3: minimum pulse width (CK) (f= 1MHz; 50% duty cycle)



5 Die Information

Die Type	RD74HC374	Wafer Size	8 Inch
Die Size (μm)	X/Y: 657/331	Bond Area (μm)	X/Y: 55/55
Scribeline (μm)	60	Chip Thickness	
Metal	Front	Al+0.5%Cu	
	Back	Si	
	Top Metal Thickness	9000Å	

(657, 331)



(0, 0)

Pin No.	Pin Name	Coordinate		Pin No.	Pin Name	Coordinate	
		X	Y			X	Y
1	$\overline{\text{OE}}$	63.5	131.5	11	CK	593.5	199.5
2	Q0	90.5	63.5	12	Q4	566.5	267.5
3	D0	158.5	63.5	13	D4	498.5	267.5
4	D1	226.5	63.5	14	D5	430.5	267.5
5	Q1	294.5	63.5	15	Q5	362.5	267.5
6	Q2	362.5	63.5	16	Q6	294.5	267.5
7	D2	430.5	63.5	17	D6	226.5	267.5
8	D3	498.5	63.5	18	D7	158.5	267.5
9	Q3	566.5	63.5	19	Q7	90.5	267.5
10	GND	593.5	131.5	20	V _{CC}	63.5	199.5

6 Ordering information

Table 9. Device summary

Order code	Package	Packing
RD74HC374BDI	DIP20	Tape and reel
RD74HC374BSO	SOP20	
RD74HC374BTS	TSSOP20	
RD74HC374B		Wafer

7 Revision history

Table 10. Document revision history ⁽¹⁾

Date	Revision	Changes
18-Jan-2022	1	Initial release
12-Dec-2023	2	Added : Die information Revised document presentation, minor textual updates

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